

# Product / Process Change Notification



N° 2019-035-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

## Flux dipping implementation for flip chip die bonding and change of lead-frame supplier for BGS 18MA14 E6327

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **18<sup>th</sup> June 2019**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates:  
“**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.


Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG  
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Chairman of the Supervisory Board: Dr. Eckart Süner  
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider  
Registered Office: Neubiberg Commercial Register  
Amtsgericht München HRB 126492

# Product / Process Change Notification



N° 2019-035-A

► **Products affected:** Please refer to attached affected product list 1\_cip19035\_a 

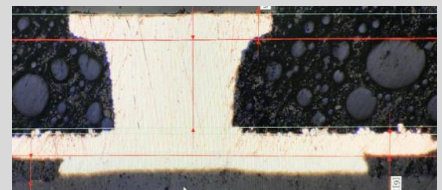
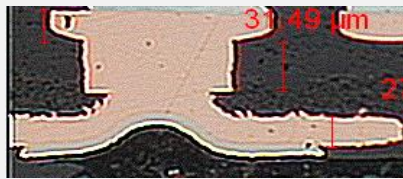
► **Detailed Change Information:**

**Subject:** Flux dipping implementation for flip chip die bonding and change of lead-frame supplier for BGS 18MA14 E6327

**Reason:** Flux dipping implementation for improvement of solder joint reliability.  
New lead-frame supplier to assure continuity and increased supply flexibility

**Description:**

	<u>Old</u>	<u>New</u>
Die bond process	■ Diffusion bonding	■ Flux dipping / reflow soldering
Leadframe supplier	■ AAPM	■ QDOS
Remark: Cross-section comparison	■ AAPM	■ QDOS



► **Product Identification:** Internal traceability ensured via baunumber, lot number & date code.  
No change in SP ordering number.

► **Impact of Change:** Based on the qualification performed, Infineon does not see any negative impact on quality, function and reliability

► **Attachments:**

Affected product list:	1_cip19035_a
Final qualification report:	2_cip19035_a

► **Time Schedule:**

■ Final qualification report:	Available
■ First samples available:	On request
■ Intended start of delivery:	15-August-2019 or earlier based on customer approval

If you have any questions, please do not hesitate to contact your local Sales office.